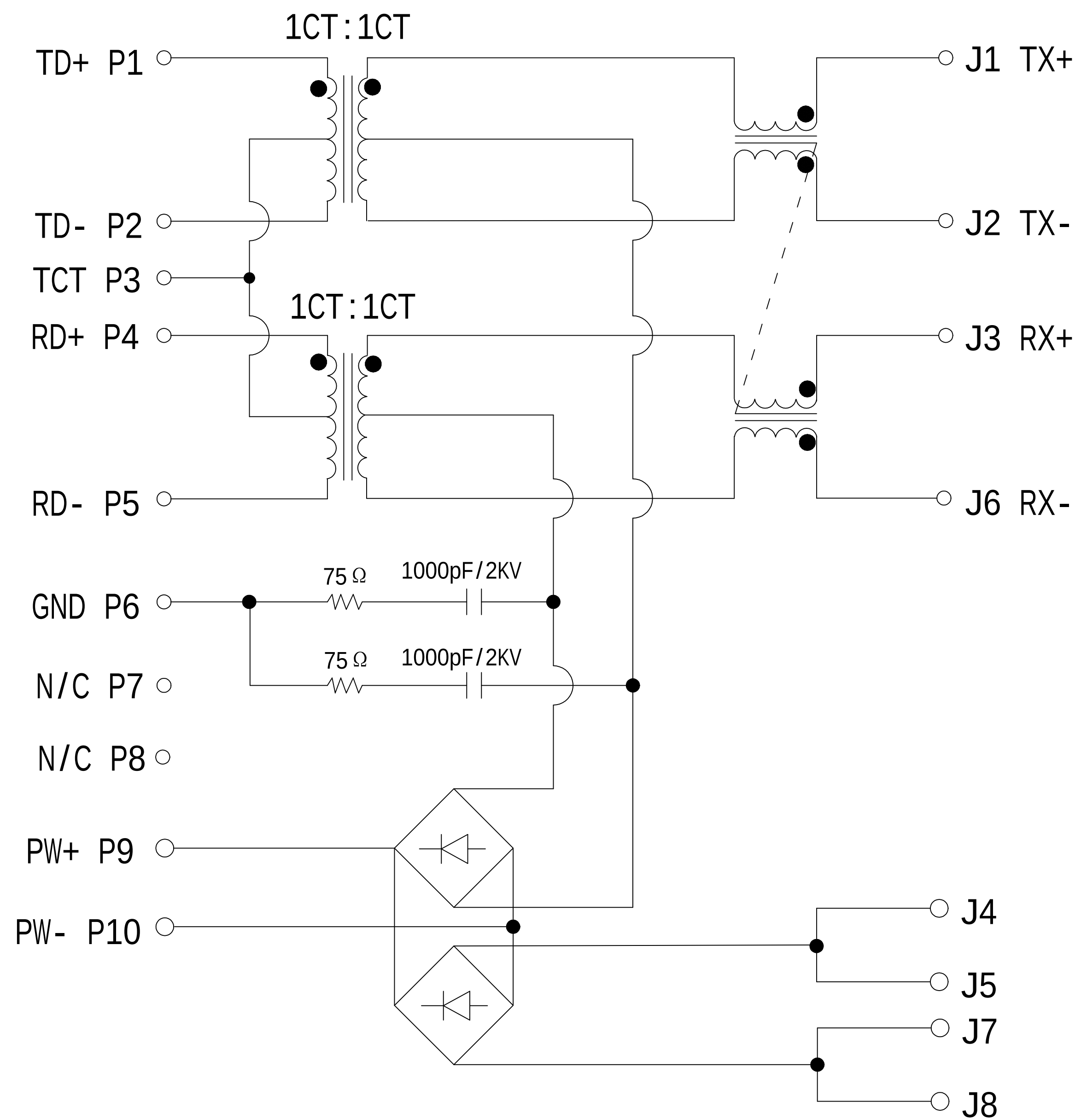


Schematic:

PC BOARD CONNECTIONS

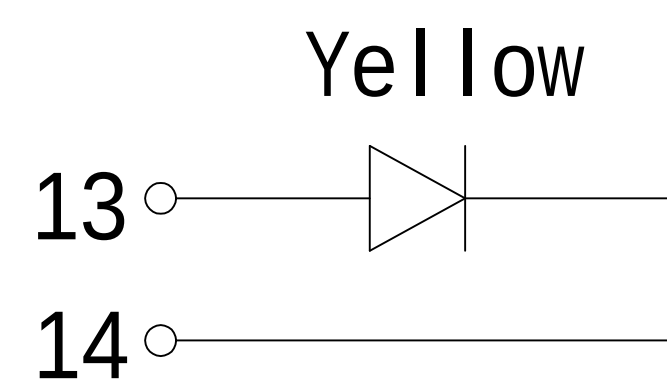


RJ45 CONNECTOR

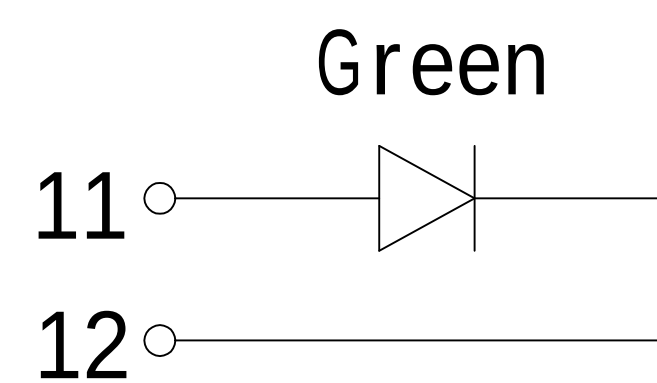
ELECTRICAL SPECIFICATIONS @25°C

- Turn Ratio($\pm 3\%$):
TX=1CT:1CT RX=1CT:1CT
- Inductance OCL:
350uH MIN @ 100KHz 0.1V 8mA DC Bias
- DCR:
1.2 Ω MAX
- Insertion Loss:
-1.1dB MAX @ 0.1-100MHz
- Return Loss:
-18dB MIN @ 0.5-30MHz
-15.5dB MIN @ 40MHz
-13.6dB MIN @ 50MHz
-12dB MIN @ 60-80MHz
- Cross talk:
-40dB TYP @ 0.1-100MHz
- Common Mode Rejection:
-50dB MIN @ 0.1-30MHz
-40dB MIN @ 30-60MHz
-35dB MIN @ 60-100MHz
- Balanced DC Line Current:
720mA MAX @48VDC
- Hipot Test: 1500Vrms
- Operating Temperature Range: -40°C TO +85°C

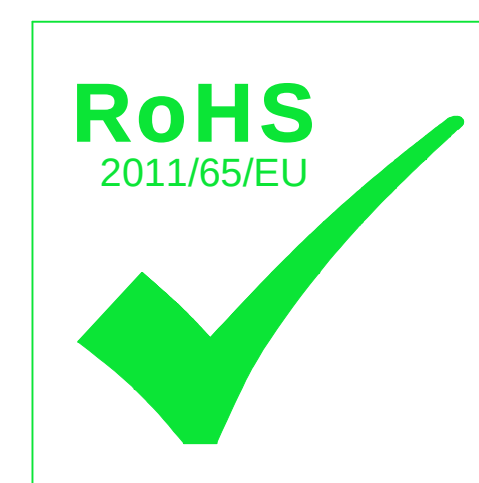
Emitting Color	λ_p (nm)	$V_F @ I_F = 20mA$	$I_R @ V_R = 5V$
Green	565	1.8~2.4V	10 μA max
Yellow	585	1.8~2.4V	10 μA max



Left LED



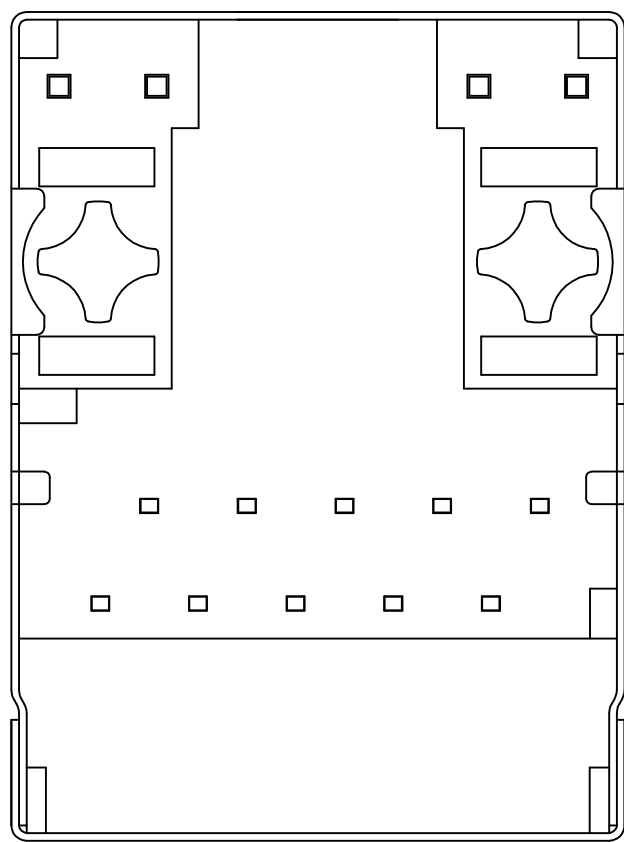
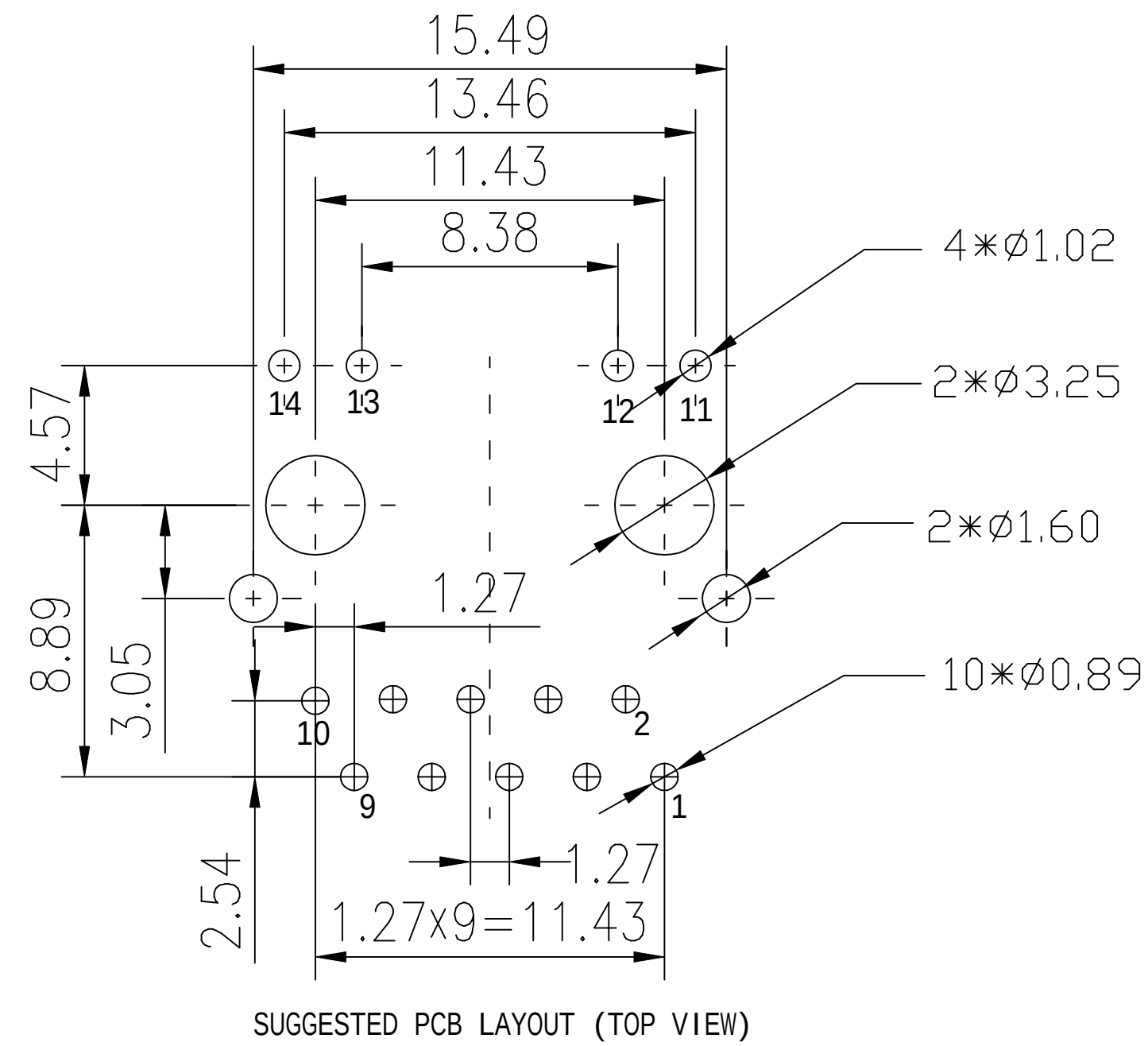
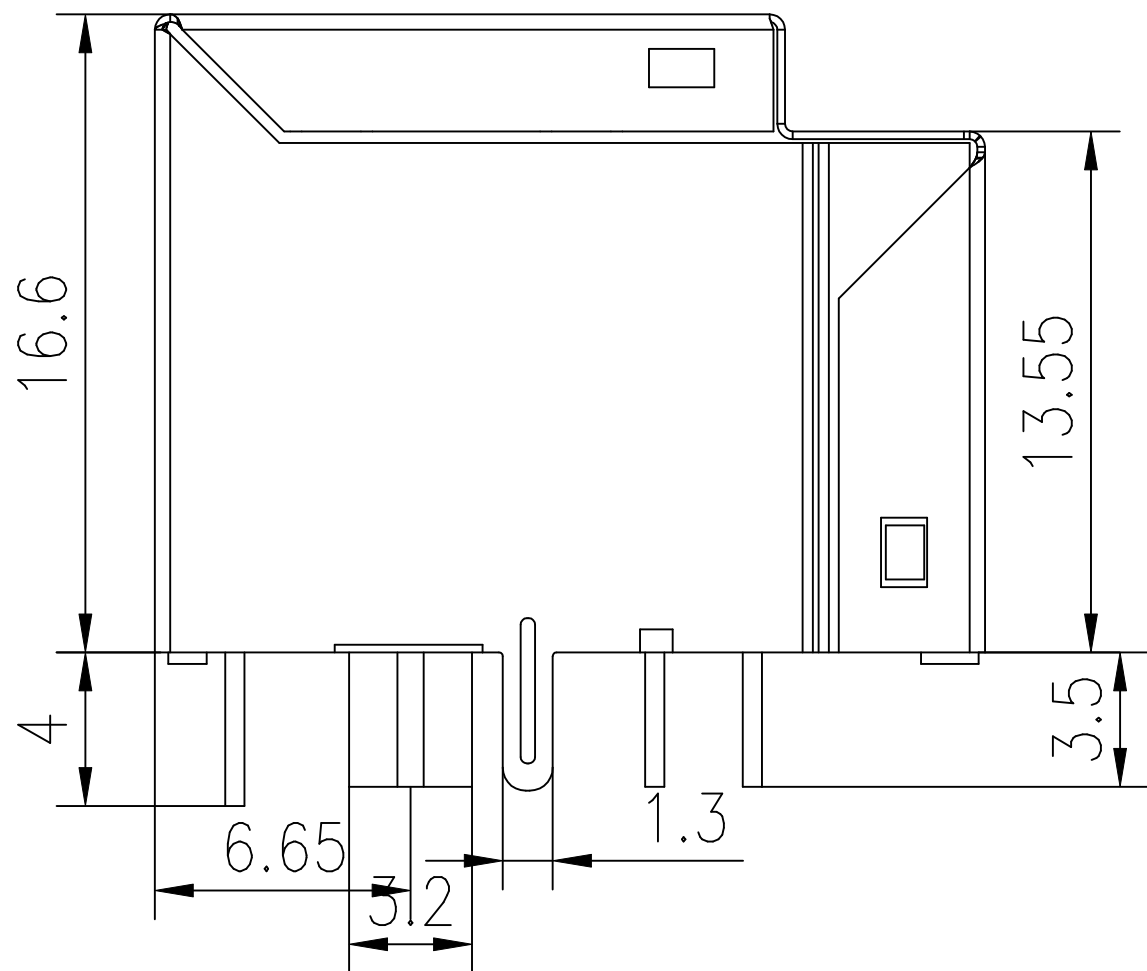
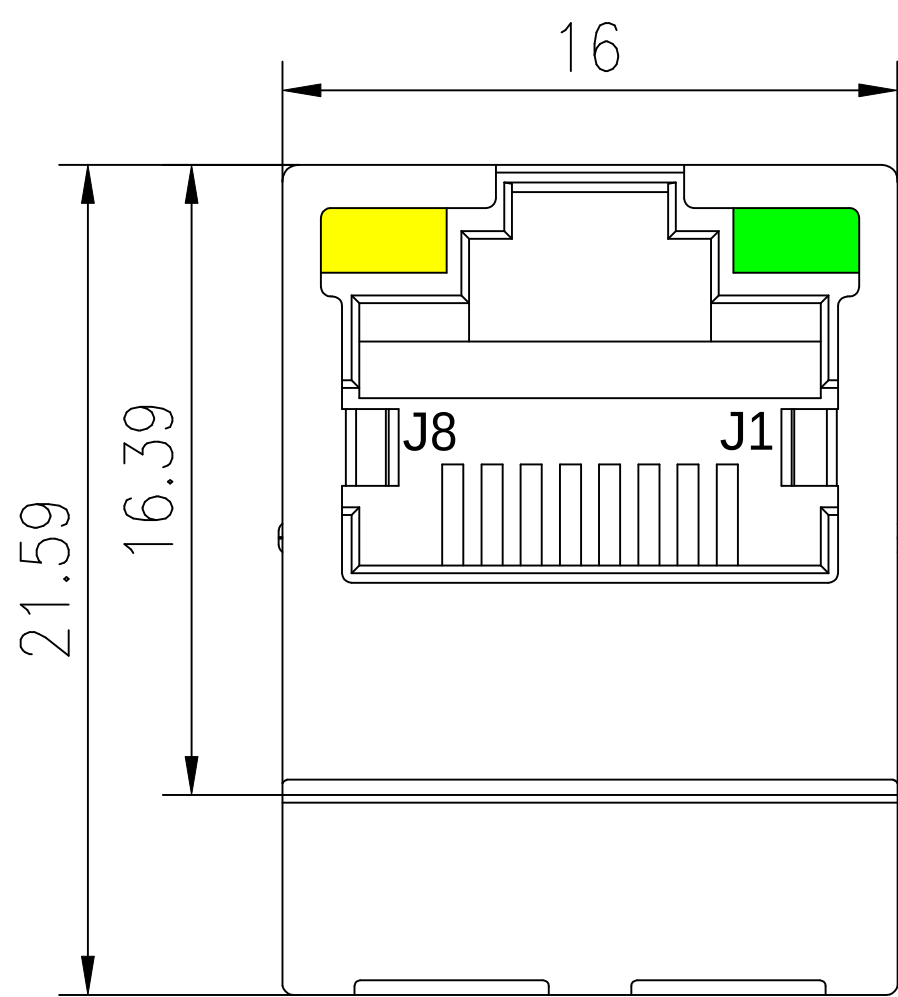
Right LED



X:X	± 0.30	APPD:	TOM	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	± 0.25	CHKD:	JAMES		
X:XXX	± 0.05	DR:	LEO	TITLE: Vertical RJ45 Connector with 10/100 Base-TX Integrated Magnetics For PoE+ Application	
ANGLES	$\pm 1^\circ$	UNIT:	mm	PART NO.: LPJDP5155BDNL	
		SCALE:	2/1	SHEET:	1/2
		REV:	A	DWG NO.: LP14031316	

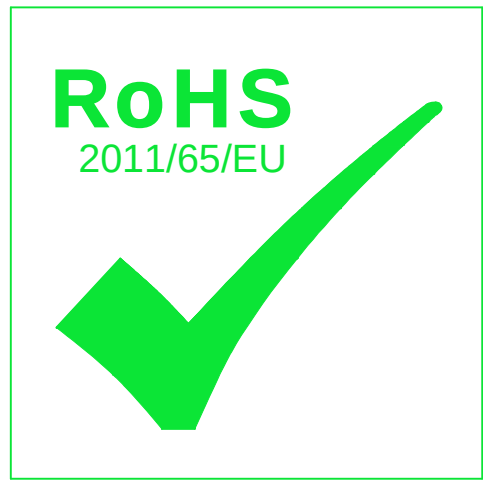
Mechanical:

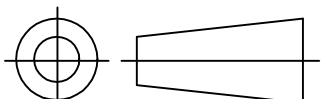
REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2016-07-09	



NOTES:

- 1.Meets IEEE 802.3af specification
- 2.Connector Materials:
Housing Material:Thermoplastic PBT+30%G.F UL94V-0
Contact Material:Phosphor Bonze C5210R-EH Thickness=0.35mm
Pins:Brass C2680R-H Thickness=0.35mm
Shield:Copper alloy Brass H65Y Thickness=0.2mm
Contact plating: Gold 6 micro-inches min.In contact area.
- 3.Wave solder tip temperature: 260°C Max, 5 Sec Max
- 4.UL Certification: File Number 484635.



X:X ±0.30		APPD: TOM		LINK-PP INT'L TECHNOLOGY CO., LIMITED		
X:XX ±0.25		CHKD: JAMES				
X:XXX ±0.05		DR: LEO		TITLE: Vertical RJ45 Connector with 10/100 Base-TX Integrated Magnetics For PoE+ Application		
ANGLES ±1°		UNIT: mm				
		PART NO.: LPJDP5155BDNL				
		SCALE: 2/1	SHEET: 2/2	REV: A	DWG NO.: LP14031316	